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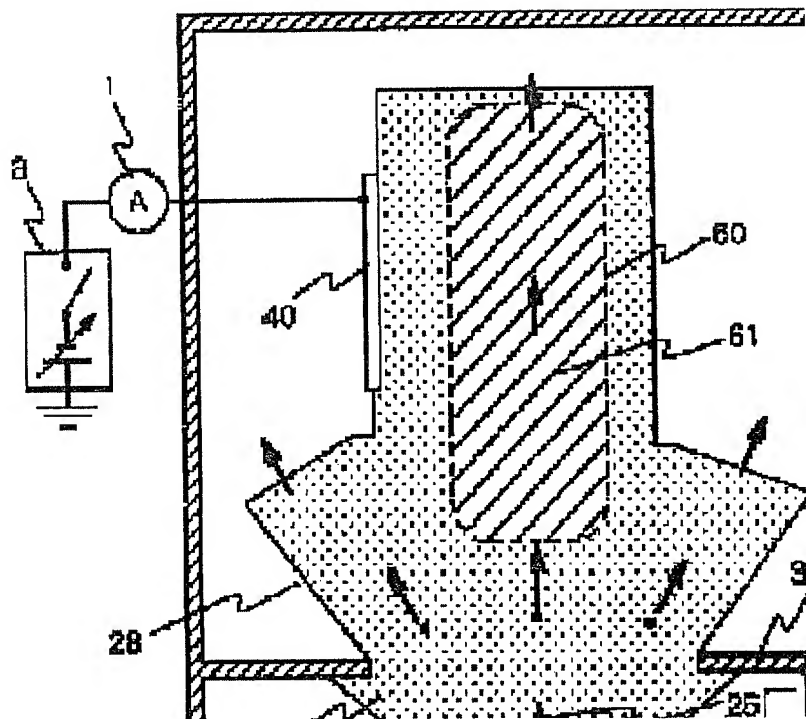
(74) Representative:

**(54) PLASMA POTENTIAL  
FIXING DEVICE AND  
PLASMA POTENTIAL  
FIXING METHOD**

(57) Abstract:

**PROBLEM TO BE SOLVED:** To provide a plasma potential fixing device in which structure is simple and separation efficiency is improved.

**SOLUTION:** A plasma potential fixing device 100 is provided with a vapor sealer 31 incorporating a laser optical path 60 and a recovery electrode 40. The laser optical path 60 ionizes an object isotope in metal vapor 25 to confine photoionization plasma 61 therein, and the recovery electrode 40 is near the laser optical path 60 to recover the object isotope. The vapor sealer 31 has a vapor slit 32 for connecting the inside and the outside thereof at its wall. The vapor slit 32 is arranged above and opposite to a crucible 29 so that the metal vapor 25 and background plasma 26 may flow into the inside through the vapor slit 32, and is



through the vapor slit 32, and is grounded, and the background plasma 26 grounded through the vapor slit 32 when passing through is diffused and makes connecting contact with the photoionization plasma 61 to fix the photoionization plasma 61 at grounding potential.

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